

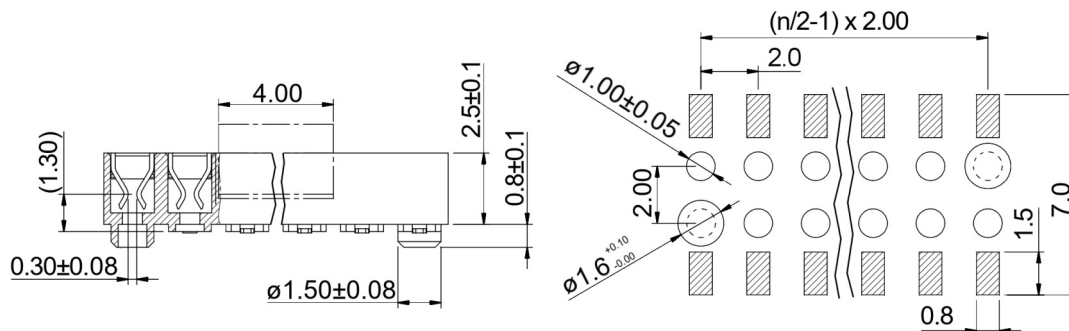
## SMT-Buchsenleisten RM 2,00mm, stehend, 2-reihig – durchsteckbar SMT Female Headers, 2.00mm Pitch, Vertical, Double Row – Pass Through

### Technische Daten / Technical Data

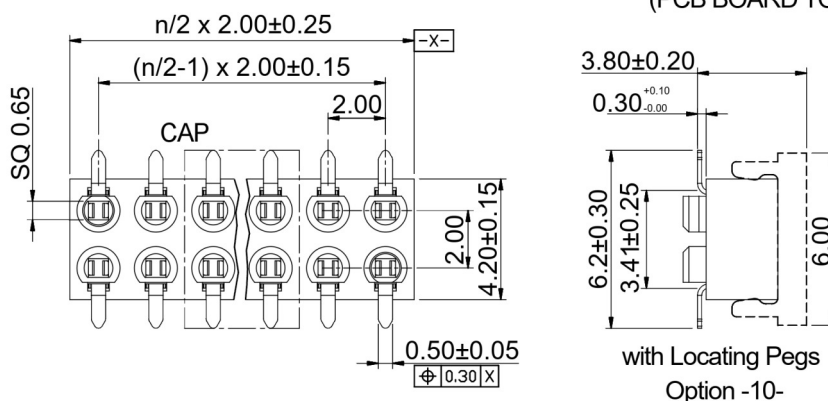
|  |  |
|--|--|
| Isolierkörper<br><i>Insulator</i>                            | Thermoplast, nach UL94 V-0<br><i>Thermoplastic, rated UL94 V-0</i>                         |
| Kontaktmaterial<br><i>Contact Material</i>                   | Kupferlegierung<br><i>Copper alloy</i>   |
| Kontaktoberfläche<br><i>Contact Surface</i>                  | Au über Ni<br><i>Au over Ni</i>  |
| RoHS-Ausnahmen 6a-I / 6c<br><i>RoHS Exemptions 6a-I / 6c</i> | keine<br><i>none</i>   |
| Durchgangswiderstand<br><i>Contact Resistance</i>            | < 20 mΩ<br><i>&lt; 20 mΩ</i>   |
| Isolationswiderstand<br><i>Insulation Resistance</i>         | > 1000 MΩ<br><i>&gt; 1000 MΩ</i>   |
| Spannungsfestigkeit<br><i>Test Voltage</i>                   | 500 V AC/DC<br><i>500 V AC/DC</i>  |
| Nennstrom<br><i>Current Rating</i>                           | 2 A<br><i>2 A</i>  |
| Temperaturbereich<br><i>Temperature Range</i>                | -40 °C ... +125 °C<br><i>-40 °C ... +125 °C</i>  |
| Verarbeitung   | 230 °C für 30-60 Sekunden<br>(260 °C für 5 Sek., Type 11)<br>(260 °C für 10 Sek., Type 30) |
| <i>Processing</i>  | 230 °C for 30-60 seconds<br>(260 °C for 5 sec., Type 11)<br>(260 °C for 10 sec., Type 30)  |



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Doppelfederkontakte für  
Vierkantstifte 0,50mm.  
*Dual beam contacts accept  
0.50mm square pins.*



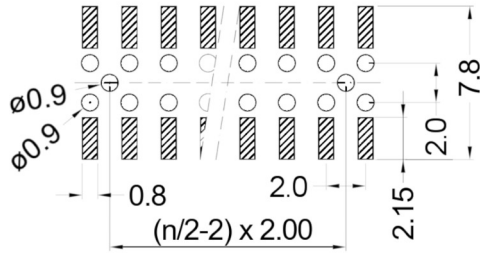
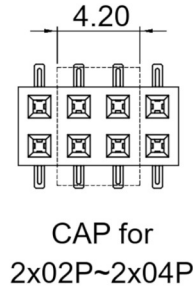
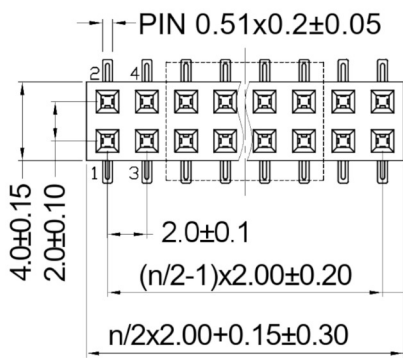
Recommended PCB Layout (Top Side)  
(PCB BOARD TOLERANCE ±0.05)



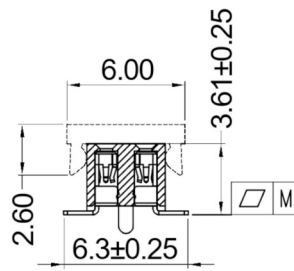
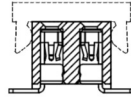
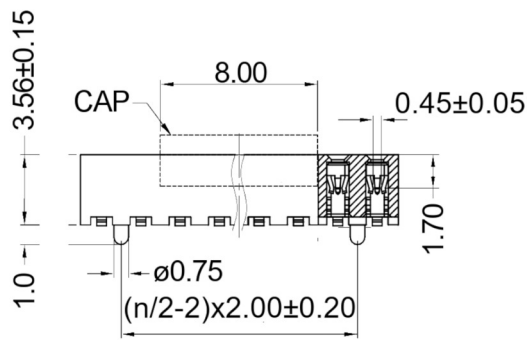
|                |                            |   |  |  |                                   |
|----------------|----------------------------|---|--|--|-----------------------------------|
| <b>Series</b>  | <b>Contacts*</b>           | <b>Type</b>   | <b>Plating</b>                           | <b>Locating Pegs</b>                             | <b>Packaging*</b>                 |
| <b>46-7450</b> | <b>20</b><br>04-44 Type 11 | <b>11</b><br>11 H=2,8mm, Eingang unten<br>H=2.8mm, bottom entry | <b>00</b><br>00 Vergoldet<br>Gold plated | <b>10</b><br>10 Mit Pos.hilfen<br>With loc. pegs | <b>PPTR</b><br>ST<br>PPST<br>PPTR |

# 46-7450

SMT-Buchsenleisten RM 2,00mm, stehend, 2-reihig – durchsteckbar  
 SMT Female Headers, 2.00mm Pitch, Vertical, Double Row – Pass Through



Recommended PCB Layout (Top Side)  
 (PCB BOARD TOLERANCE ±0.05)



| Series         | Contacts*                  | Type  | Plating                               | Locating Pegs*  | Packing*  |
|----------------|----------------------------|---|---------------------------------------|---|---|
| <b>46-7450</b> | <b>20</b><br>04-50 Type 30 | <b>30</b><br>30 H=3,6mm, Eingang oben<br>H=3.6mm, top entry | <b>00</b><br>Vergoldet<br>Gold plated | <b>10</b><br>00 Ohne Pos.hilfen<br>W/o loc. pegs<br>10 Mit Pos.hilfen<br>With loc. pegs | <b>PPTR</b><br>ST In Stangen ohne Pick&Place-Pads<br>In tubes w/o Pick&Place-Pads<br>PPST In Stangen mit Pick&Place-Pads<br>In tubes with Pick&Place-Pads<br>PPTR Tape & Reel mit Pick&Place-Pads<br>Tape & Reel with Pick&Place-Pads |

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
 \* This is an **order example** - please replace by your specifications.

**Lieferformen / Packaging Options:**  
 ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads  
 PPST In Stangen mit Pick&Place-Pads / In tubes with Pick&Place-Pads  
 PPTR Tape & Reel mit Pick&Place-Pads / Tape & Reel with Pick&Place-Pads

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft                    | Kennwert                        |
|--------------------------------------|---------------------------------|
| Temperatur Minimum $T_{Smin}$        | 150 °C                          |
| Temperatur Maximum $T_{Smax}$        | 200 °C                          |
| Dauer $T_{Smin} - T_{Smax}$          | 60 – 180s                       |
| Temperatur Lötbereich $T_L$          | untere Temperaturangabe [°C]    |
| Verweildauer oberhalb $T_L$          | laut Angabe im Datenblatt [sec] |
| Ramp-Up Rate $T_{Smax} - T_P$        | max. 3 °C / s                   |
| Höchsttemperatur $T_P$               | obere Temperaturangabe [°C]     |
| Dauer Höchsttemperatur               | laut Angabe im Datenblatt [sec] |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s                        |
| Dauer 25 °C – Höchsttemperatur $T_P$ | max. 8m                         |

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature                      | Key Values              |
|--------------------------------------|-------------------------|
| Minimum Temperature $T_{Smin}$       | 150 °C                  |
| Maximum Temperatur $T_{Smax}$        | 200 °C                  |
| Duration $T_{Smin} - T_{Smax}$       | 60 – 180s               |
| Soldering Range Temperature $T_L$    | Lower Temperature [°C]  |
| Duration above $T_L$                 | Acc. to datasheet [sec] |
| Ramp-Up Rate $T_{Smax} - T_P$        | max. 3 °C / s           |
| Peak Temperature $T_P$               | Upper Temperature [°C]  |
| Duration Peak Temperature            | Acc. to datasheet [sec] |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s                |
| Duration 25°C - Peak Temp. $T_P$     | max. 8min               |

